LEAD FORMING GUIDELINES:

APPLY THE FOLLOWING LEAD FORMING GUIDELINES TO ENSURE THE 288-LEAD CERAMIC QFP WILL FIT ONTO THIS FOOTPRINT.

1) FIRST LEAD BEND IS 1.14 ± 0.13 (.045 ± 0.005) FROM THE BODY.
2) SECOND LEAD BEND IS MADE 2.61 ±0.51 (.105 ±0.020) TO ALLOW PCB TO COMPONENT BODY CLEARANCE.
3) THE HEAL OF THE FOOT IS OFFSET FROM THE FIRST BEND BY 0.46 (.018).
4) THE FOOT OF THE LEAD IS 1.14 ± 0.13 (.045 ± 0.005).

THESE LEAD FORMING GUIDELINES ARE COMPATABLE WITH IPC/EIA J-STD-001C FOR NOMINAL SOLDER FILLETS AND IPC-SM-782 FOR LAND PATTERN DESIGN.

RECOMMENDED FOOTPRINT FOR AEROFLEX 288-PIN CERAMIC QUAD FLAT PACKAGE (CQFP)